



Material Composition Declaration

EPC2107

Company Name	Efficient Power Conversion (EPC)	Issue Date:	9/22/2017
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	3.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	2.6104	87.5892	90.0838	875892
	Silicon oxide	7631-86-9	0.0119	0.3977		3977
	Silicon nitride	12033-89-5	0.0040	0.1345		1345
	Gallium nitride	25617-97-4	0.0135	0.4539		4539
	Aluminum	7429-90-5	0.0179	0.6006		6006
	Aluminum nitride	24304-00-5	0.0033	0.1091		1091
	Titanium	7440-32-6	0.0004	0.0137		137
	Titanium nitride	25583-20-4	0.0016	0.0546		546
	Copper	7440-50-8	0.0006	0.0200		200
	Tungsten	7440-33-7	0.0002	0.0065		65
	Polyimide		0.0210	0.7039		7039
Under Bump Metal	Titanium	7440-32-6	0.0002	0.0060	0.5098	60
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.0150	0.5038		5038
Solder Bump	Tin	7440-31-5	0.2677	8.9831	9.4064	89831
	Silver	7440-22-4	0.0112	0.3763		3763
	Copper	7440-50-8	0.0014	0.0470		470
Sum in total:			2.9803	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.